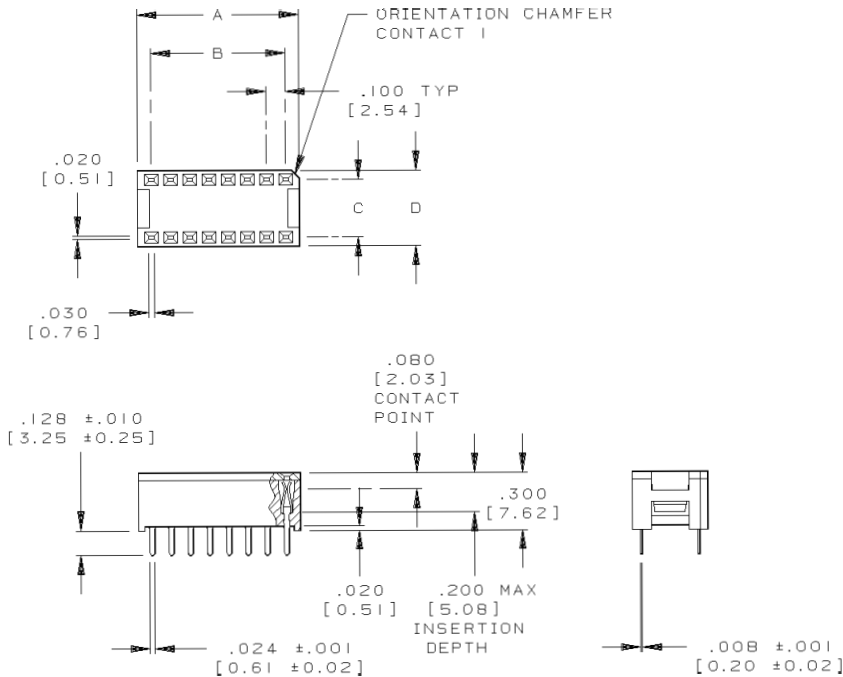




DIP SOCKET .300 HIGH SOLDER TAIL



FEATURES

.024 [0.61] X .008 [0.20] solder tail
 Dual leaf edge wipe contacts
 designed to mate with DIP packages on .100 [2.54] centers

SPECIFICATIONS ENVIRONMENTAL

Temperature Range: -65°C to +105°C

MECHANICAL

Insulator Material:
 Glass filled polyester, black, UL94V-0

Contact Material:
 Phosphor Bronze

Contact Plating:

Standard

10µ IN gold

Optional

250µ IN tin

Contact Insertion Force:

6.2 oz [1.7 N] TYP

10.6 oz [2.9 N] MAX

Contact Extraction Force:

1.8 oz [0.5 N] TYP

0.7 oz [0.2 N] MIN

Measured with .0145 [0.37] dia. pin

Recommended Mating Pin Size:

.022 [0.56] X .020 [0.51] MAX

.010 [0.25] X .008 [0.20] MIN

ELECTRICAL

Current Rating:

1 AMP

Voltage Rating:

250 Vrms

Dielectric Withstanding

Voltage: 500 Vrms MIN

Insulation Resistance:

> 5000 Megohms

Contact Resistance:

10 milliohms TYP

30 milliohms MAX

MATING CA PRODUCT:

IDP, IDP2, MP, P

No. of Positions	Dimensions				Contact Plating	Part Numbers Phosphor Bronze
	A	B	C	D		
10	.545	.400	.200	.295	10µ IN gold	CA-10S-10SD
	[13.84]	[10.16]	[5.08]	[7.49]	250µ IN tin	CA-10S-TSD
14	.745	.600	.300	.395	10µ IN gold	CA-14S-10SD
	[17.73]	[15.24]	[7.62]	[10.03]	250µ IN tin	CA-14S-TSD
16	.845	.700	.300	.395	10µ IN gold	CA-16S-10SD
	[21.46]	[17.78]	[7.62]	[10.03]	250µ IN tin	CA-16S-TSD
18	.945	.800	.300	.395	10µ IN gold	CA-18S-10SD
	[24.00]	[20.32]	[7.62]	[10.03]	250µ IN tin	CA-18S-TSD
20	1.045	.900	.300	.395	10µ IN gold	CA-20S-10SD
	[26.54]	[22.86]	[7.62]	[10.03]	250µ IN tin	CA-20S-TSD
24	1.245	1.100	.600	.695	10µ IN gold	CA-24S-10SD
	[31.62]	[27.94]	[15.24]	[17.65]	250µ IN tin	CA-24S-TSD
28	1.445	1.300	.600	.695	10µ IN gold	CA-28S-10SD
	[36.70]	[33.02]	[15.24]	[17.65]	250µ IN tin	CA-28S-TSD
40	2.045	1.900	.600	.695	10µ IN gold	CA-40S-10SD
	[51.94]	[48.26]	[15.24]	[17.65]	250µ IN tin	CA-40S-TSD